## **Zener Voltage Regulators**

### 500 mW SOD-123 Surface Mount

Three complete series of Zener diodes are offered in the convenient, surface mount plastic SOD-123 package. These devices provide a convenient alternative to the leadless 34-package style.

### **Features**

- 500 mW Rating on FR-4 or FR-5 Board
- Wide Zener Reverse Voltage Range 1.8 V to 43 V
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- Peak Power 225 W (8 x 20 μs)
- AEC-Q101 Qualified and PPAP Capable
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Packages are Available\*

#### **Mechanical Characteristics:**

CASE: Void-free, transfer-molded, thermosetting plastic case

FINISH: Corrosion resistant finish, easily solderable

### MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:

260°C for 10 Seconds

**POLARITY:** Cathode indicated by polarity band

FLAMMABILITY RATING: UL 94 V-0

### **MAXIMUM RATINGS**

Rating	Symbol	Max	Unit
Peak Power Dissipation @ 20 μs (Note 1) @ T <sub>L</sub> ≤ 25°C	P <sub>pk</sub>	225	W
Total Power Dissipation on FR–5 Board, (Note 2) @ T <sub>L</sub> = 75°C Derated above 75°C	P <sub>D</sub>	500 6.7	mW mW/°C
Thermal Resistance, (Note 3) Junction-to-Ambient	$R_{\theta JA}$	340	°C/W
Thermal Resistance, (Note 3) Junction-to-Lead	$R_{ heta JL}$	150	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Nonrepetitive current pulse per Figure 11.
- 2.  $FR-5 = 3.5 \times 1.5$  inches, using the minimum recommended footprint.
- 3. Thermal Resistance measurement obtained via infrared Scan Method.

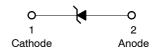


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SOD-123 CASE 425 STYLE 1



### **MARKING DIAGRAM**



xxx = Device Code (Refer to page 2)

M = Date Code ■ = Pb-Free Package

(Note: Microdot may be in either location)

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMSZ4xxxET1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel
SZMMSZ4xxxET1G	SOD-123 (Pb-Free)	3,000 / Tape & Reel
MMSZ4xxxET3G	SOD-123 (Pb-Free)	10,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

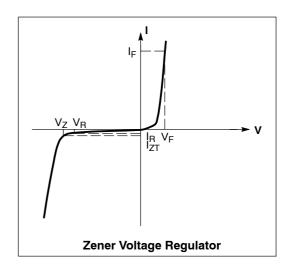
### **DEVICE MARKING INFORMATION**

See specific marking information in the device marking column of the Electrical Characteristics table on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 0.95$ V Max. @ $I_F = 10$ mA)

Symbol	Parameter			
VZ	Reverse Zener Voltage @ I <sub>ZT</sub>			
I <sub>ZT</sub>	Reverse Current			
I <sub>R</sub>	Reverse Leakage Current @ V <sub>R</sub>			
V <sub>R</sub>	Reverse Voltage			
IF	Forward Current			
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>			



### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 0.9$ V Max. @ $I_F = 10$ mA)

		Zener Voltage (Note 1)				Leakage Current	
	Device	V <sub>Z</sub> (V)			@ I <sub>ZT</sub>	I <sub>R</sub> @	V <sub>R</sub>
Device*	Marking	Min	Nom	Max	μА	μА	V
MMSZ4680ET1G	CF8	2.09	2.2	2.31	50	4	1
MMSZ4684ET1G	CG3	3.13	3.3	3.47	50	7.5	1.5
MMSZ4688ET1G	CG7	4.47	4.7	4.94	50	10	3
MMSZ4689ET1G	CG8	4.85	5.1	5.36	50	10	3
MMSZ4690ET1G	CG9	5.32	5.6	5.88	50	10	4
MMSZ4691ET1G	CH1	5.89	6.2	6.51	50	10	5
MMSZ4692ET1G	CH2	6.46	6.8	7.14	50	10	5.1
MMSZ4693ET1G	СНЗ	7.13	7.5	7.88	50	10	5.7
MMSZ4697ET1G	CH7	9.50	10	10.50	50	1	7.6
MMSZ4699ET1G	CH9	11.40	12	12.60	50	0.05	9.1
MMSZ4701ET1G	CJ2	13.3	14	14.7	50	0.05	10.6
MMSZ4702ET1G	CJ3	14.25	15	15.75	50	0.05	11.4
MMSZ4703ET1G	CJ4	15.20	16	16.80	50	0.05	12.1
MMSZ4705ET1G	CJ6	17.10	18	18.90	50	0.05	13.6
MMSZ4709ET1G	CK1	22.80	24	25.20	50	0.01	18.2
MMSZ4711ET1G	СКЗ	25.65	27	28.35	50	0.01	20.4
MMSZ4717ET1G	CK9	40.85	43	45.15	50	0.01	32.6

<sup>1.</sup> Nominal Zener voltage is measured with the device junction in thermal equilibrium at  $T_L = 30^{\circ}C \pm 1^{\circ}C$ .

<sup>\*</sup>Include SZ-prefix devices where applicable.

### **TYPICAL CHARACTERISTICS**

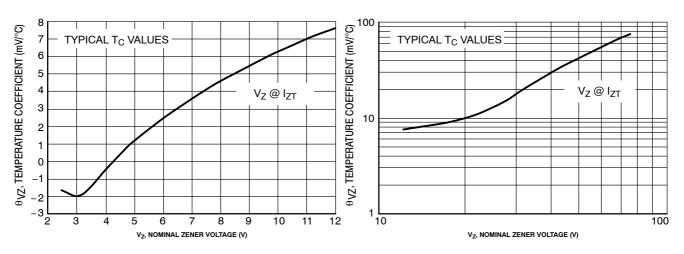


Figure 1. Temperature Coefficients (Temperature Range – 55°C to +150°C)

Figure 2. Temperature Coefficients (Temperature Range – 55°C to +150°C)

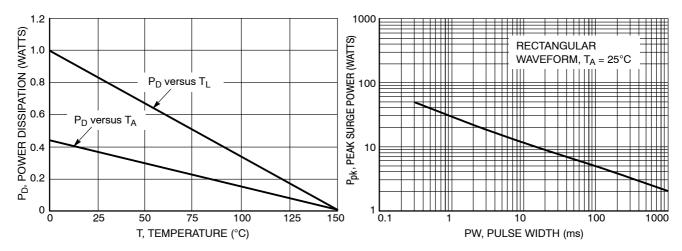


Figure 3. Steady State Power Derating

Figure 4. Maximum Nonrepetitive Surge Power

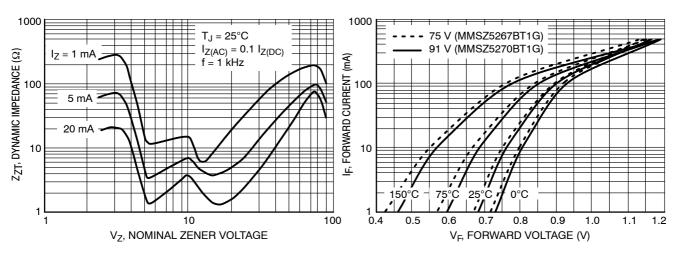


Figure 5. Effect of Zener Voltage on Zener Impedance

Figure 6. Typical Forward Voltage

### **TYPICAL CHARACTERISTICS**

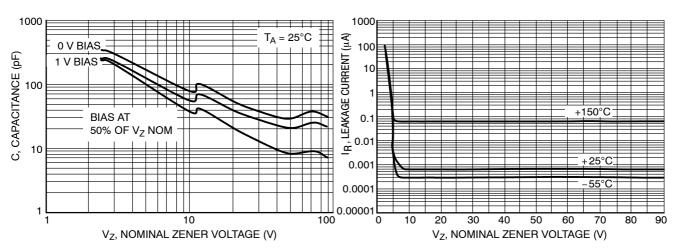


Figure 7. Typical Capacitance

Figure 8. Typical Leakage Current

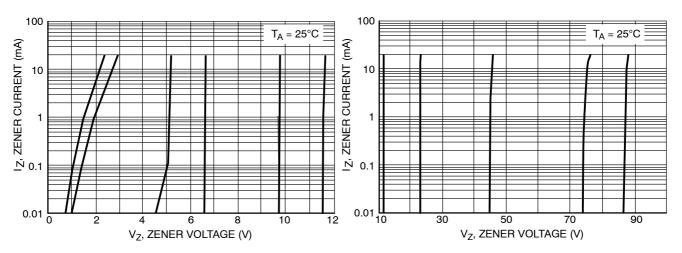


Figure 9. Zener Voltage versus Zener Current (V<sub>Z</sub> Up to 12 V)

Figure 10. Zener Voltage versus Zener Current (12 V to 91 V)

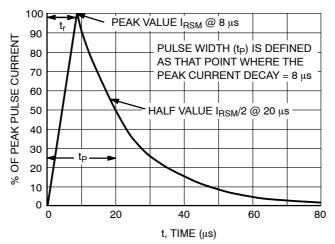


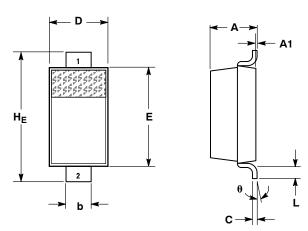
Figure 11. 8  $\times$  20  $\mu s$  Pulse Waveform



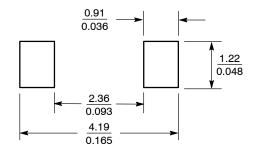
SOD-123 CASE 425-04 ISSUE G

**DATE 07 OCT 2009** 





### **SOLDERING FOOTPRINT\***



SCALE 10:1

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.94	1.17	1.35	0.037	0.046	0.053	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
b	0.51	0.61	0.71	0.020	0.024	0.028	
С			0.15			0.006	
D	1.40	1.60	1.80	0.055	0.063	0.071	
Е	2.54	2.69	2.84	0.100	0.106	0.112	
HE	3.56	3.68	3.86	0.140	0.145	0.152	
L	0.25			0.010			
θ	0°		10°	0°		10°	

### **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

STYLE 1: PIN 1. CATHODE 2. ANODE

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DESCRIPTION:	SOD-123		PAGE 1 OF 1	

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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